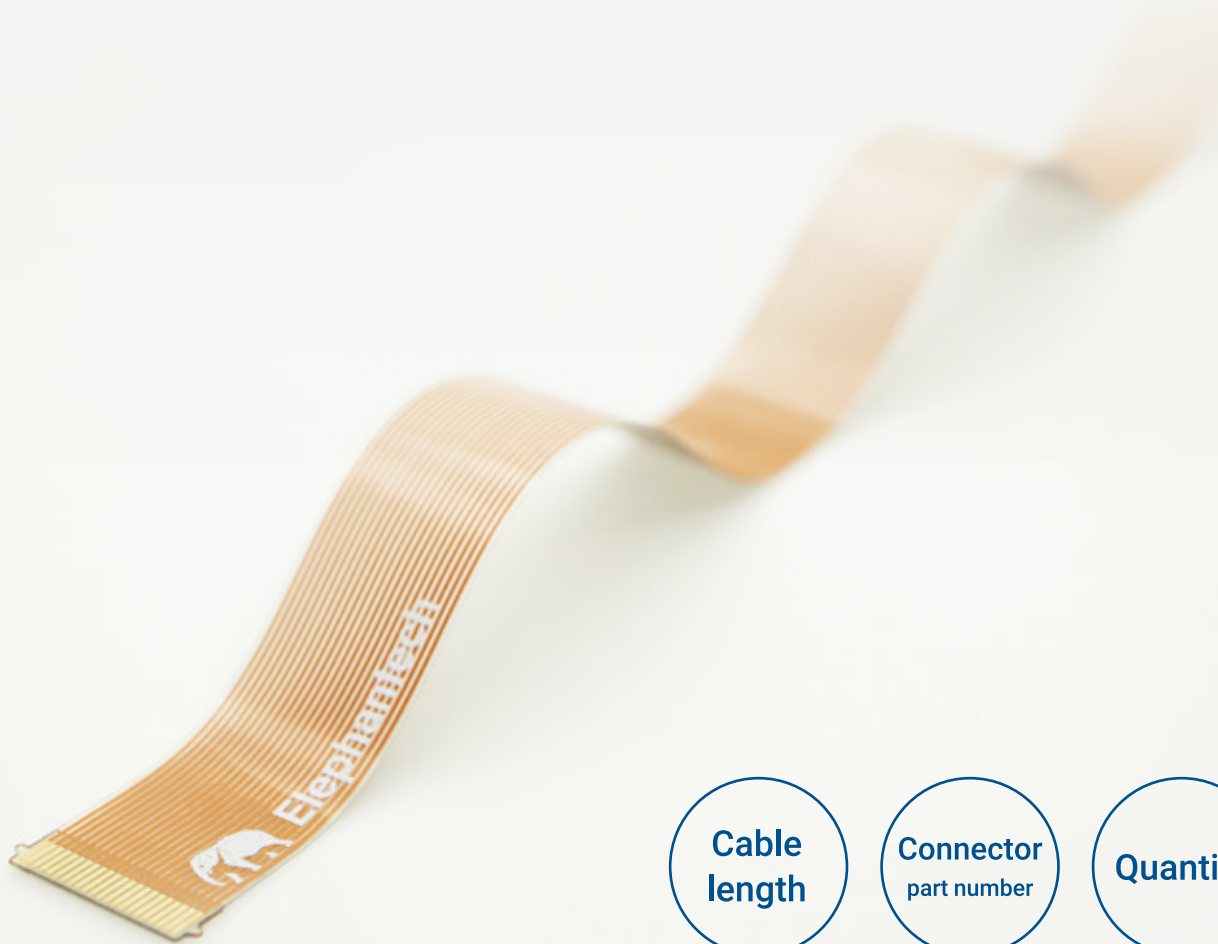




Elephantech

P-Flex[®] PET Applications

Custom single-sided flexible flat cable



Cable
length

Connector
part number

Quantity

Provide estimate with above information

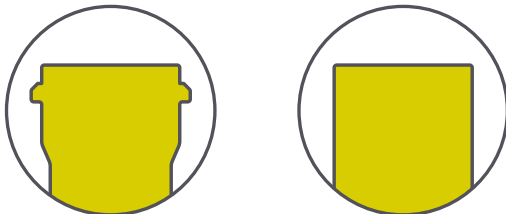
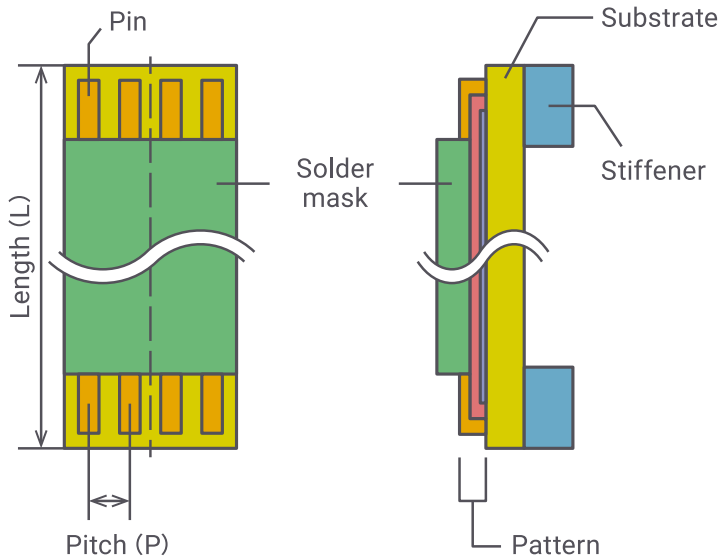
Merits

With inkjet patterning / photo mask and mold less manufacturing, various custom requests are acceptable. We can make cables of any shape and pin count according to your request regardless of quantity.

- ✓ Quick delivery by photomask and mold less manufacturing
- ✓ Supports pitch conversion cables such as 0.5 mm ↔ 0.4 mm
- ✓ Complex connector shapes such as with ears are available
- ✓ Custom L or S shaped cuttings are also available as an option

Please contact us using the contact information on the back

Basic Specifications for Custom single-sided flexible flat cable



Examples of connector shapes

Main specifications

Available pin count	4 pin ~ 100 pin
Available pitch	0.4 (Special specifications), 0.5, 0.8, 1.0, 1.25 (mm)
Cable length	30 ~ 260 (mm)
Exposed contacts	Same side
Copper foil thickness	3 μm, 6μm (Special specifications)
Terminal finish	Electroless Ni-Au plating
Stiffener material	PET, Polyimide
Total thickness of the connector connection	0.2, 0.3 mm approximately
Substrate	PET 50 μm, 125 μm, Polyimide 25 μm

*Please note that 0.3mm pitch connectors are not yet available. Also, we may not be able to comply with demands depending on the connector shape.

Compatible connectors

Manufacturer name: HIROSE, Molex, Panasonic, JST (Japanese Solderless Terminals Co., Ltd.) and others.
Please contact us for details such as part numbers.

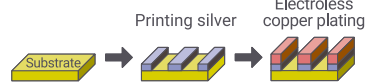
About P-Flex®

About Elephantech's manufacturing method (Pure Additive™ processing)

This manufacturing method consists of inkjet-printing silver nano-ink onto the substrate before electroless copper plating is applied to form the circuit. By reducing the amount of metal, liquid waste and man-hours, we can lessen manufacturing costs and shorten the lead time.

(* Patent No. 6300213 acquired)

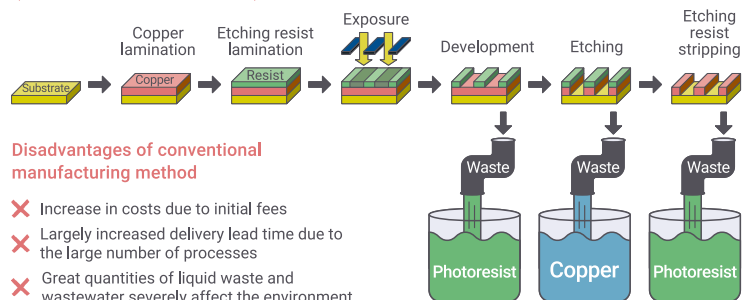
Elephantech's manufacturing method (Pure Additive™ processing)



Advantages of Elephantech's manufacturing method

- ✓ Forming the circuit only where needed allows for a reduction in manufacturing cost and environmental footprint.
- ✓ A simple manufacturing process allowing for a shorter lead time.

Conventional manufacturing method (subtractive method)



Disadvantages of conventional manufacturing method

- ✗ Increase in costs due to initial fees
- ✗ Largely increased delivery lead time due to the large number of processes
- ✗ Great quantities of liquid waste and wastewater severely affect the environment

P-Flex® manufacturing specifications

Substrate	Transparent heat-resistant PET film: 50 μm thick, 125 μm thick PI (Polyimide) film: 25 μm thick
Line width / spacing	200/200 μm min., 200/150 μm min. (only PET substrate option)
Outline-pattern spacing	0.3 mm min.
Operating temperature	Between -20°C and +105°C
Copper foil thickness	3 μm (Please contact us for more than 3 μm)
Panel size	180 × 270 mm max.
Wiring layer	Single-sided
Soldermask coating (PET)	UV inkjet printing (transparent)
Coverlay pasting (PI)	PI film 12.5 μm, adhesion layer 15 μm
Legend printing	UV inkjet printing (white)
Surface finish	Oxidation prevention treatment, Electroless nickel gold plating (option)
Outline cutting / Hole drilling	Laser cutting
Stiffeners	Wide range of material and thickness
PCBA Service	Available. Subject to negotiation.

Company Overview



Elephantech

Elephantech Inc.
(Formerly AgIC Inc.*)

*Changed corporate name on September 4, 2017

Website



Contact



Establishment	January 6, 2014
Address	4-3-8 Hatchobori, Chuo-ku, Tokyo 104-0032, Japan
Capital	JPY 310 million
Representative	Shinya Shimizu, CEO
Website	https://www.elephantech.co.jp/en/
Contact	https://www.elephantech.co.jp/en/about/#contact